

<b>INFORMATION DISCLOSURE CITATION</b> <i>(Use several sheets if necessary)</i>				Docket Number (Optional) DC5157PCT1		Application Number <b>107565916</b>	
				Applicant(s) TAMMY CHENG		et al.	
				Filing Date		Group Art Unit 10565916 - GAU: 2813	

  

U.S. PATENT DOCUMENTS							
*EXAMINER INITIAL	REF	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
		4,293,479	06-Oct-1981	Hanada, et. al.	260	37	
		4,327,369	27-Apr-1982	Kaplan	357	72	
		4,663,397	05-May-1987	Morita, et. al.	525	398	
		4,778,860	18-Oct-1988	Morita	525	431	
		4,880,882	14-Nov-1989	Morita, et. al.	525	446	

  

U.S. PATENT APPLICATION PUBLICATIONS							
*EXAMINER INITIAL	REF	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
		2001/0040283 A1	15-Nov-2001	Konishi, et. al.	257	687	

  

FOREIGN PATENT DOCUMENTS							
REF	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						YES	NO
	WO 2003/041130 A2	20-Sep-2002	EP				
	WO 2000/047391 A1	17-Aug-2000	EP				
	EP 0 685 508 B1	06-May-1999	EP				
	EP 0 707 042 B1	11-Mar-1998	EP				
	JP 83834/03	25-Mar-2003	JP				

  

OTHER DOCUMENTS		(Including Author, Title, Date, Pertinent Pages, Etc.)
		Harper, Charles A., Ed., "Packaging Assembly Process," Packaging and Interconnection Handbook, 2nd ed., pp. 6.66-6.77, McGraw-Hill, New York, 1997.
		Kroschwitz, J., ed., "Electronic Materials," Kirk-Othmer Encyclopedia of Chemical Technology, 4th ed., vol. 9, pp.219-229, John Wiley & Sons, New York, 1994.

  

EXAMINER	/Stephen W. Smoot/	DATE CONSIDERED	05/15/2009
----------	--------------------	-----------------	------------

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP Section 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

<b>INFORMATION DISCLOSURE CITATION</b> <i>(Use several sheets if necessary)</i>				Docket Number (Optional) DC5157PCCT1		Application Number <b>10/565916</b>	
				Applicant(s) TAMMY CHENG		et al.	
				Filing Date		Group Art Unit 10565916 - GAU: 2813	

  

U.S. PATENT DOCUMENTS							
*EXAMINER INITIAL	REF	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
		5,387,624	07-Feb-1995	Morita, et. al.	523	220	
		5,492,945	20-Feb-1996	Morita, et. al.	523	212	
		5,691,401	25-Nov-1997	Morita, et. al.	523	435	
		5,933,713	03-Aug-1999	Farnworth	438	127	

  

U.S. PATENT APPLICATION PUBLICATIONS							
*EXAMINER INITIAL	REF	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE

  

FOREIGN PATENT DOCUMENTS								
REF	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation		
						YES	NO	

  

OTHER DOCUMENTS		(Including Author, Title, Date, Pertinent Pages, Etc.)
		Abstract, DE 19801657, July 29, 1999.
		Abstract, "The Lead Plastic Chip Carrier - its Reliability and Use." Brodsky, et. al., January 1, 1981.
		Hmiel, Andrew F., et. al., "A Novel Process for Protecting Wire Bonds from Sweep During Molding.", SEMICON West 2002 Technology Symposium.

  

EXAMINER	/Stephen W. Smoot/	DATE CONSIDERED	05/15/2009
----------	--------------------	-----------------	------------

  

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP Section 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.